SN74LVC157A-EP QUADRUPLE 2-LINE TO 1-LINE DATA SELECTOR/MULTIPLEXER

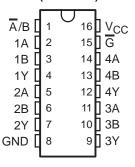
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- Controlled Baseline
 - One Assembly/Test Site, One Fabrication Site
- Extended Temperature Performance of -40°C to 125°C
- Enhanced Diminishing Manufacturing Sources (DMS) Support
- Enhanced Product-Change Notification
- Qualification Pedigree[†]
- ESD Protection Exceeds 2000 V Per MIL-STD-883, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)

† Component qualification in accordance with JEDEC and industry standards to ensure reliable operation over an extended temperature range. This includes, but is not limited to, Highly Accelerated Stress Test (HAST) or biased 85/85, temperature cycle, autoclave or unbiased HAST, electromigration, bond intermetallic life, and mold compound life. Such qualification testing should not be viewed as justifying use of this component beyond specified performance and environmental limits.

- Operates From 2 V to 3.6 V
- Inputs Accept Voltages to 5.5 V
- Max t_{pd} of 5.4 ns at 3.3 V
- Typical V_{OLP} (Output Ground Bounce)
 <0.8 V at V_{CC} = 3.3 V, T_A = 25°C
- Typical V_{OHV} (Output V_{OH} Undershoot)
 2 V at V_{CC} = 3.3 V, T_A = 25°C

D OR PW PACKAGE (TOP VIEW)



description/ordering information

The SN74LVC157A-EP quadruple 2-line to 1-line data selector/multiplexer is designed for 2.7-V to 3.6-V V_{CC} operation.

This device features a common strobe (\overline{G}) input. When \overline{G} is high, all outputs are low. When \overline{G} is low, a 4-bit word is selected from one of two sources and is routed to the four outputs. The device provides true data.

Inputs can be driven from either 3.3-V or 5-V devices. This feature allows the use of this device as a translator in a mixed 3.3-V/5-V system environment.

ORDERING INFORMATION

TA	PACK	AGE [‡]	ORDERABLE PART NUMBER	TOP-SIDE MARKING
-40°C to 125°C	SOIC - D	Tape and reel	SN74LVC157AQDREP	C157AEP
-40 C to 125°C	TSSOP - PW	Tape and reel	SN74LVC157AQPWREP	C157AEP

[‡] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

FUNCTION TABLE

	INPU	JTS		OUTPUT
G	Ā/B	Α	В	Υ
Н	Χ	Χ	Χ	L
L	L	L	X	L
L	L	Н	X	Н
L	Н	Χ	L	L
L	Н	Χ	Н	Н

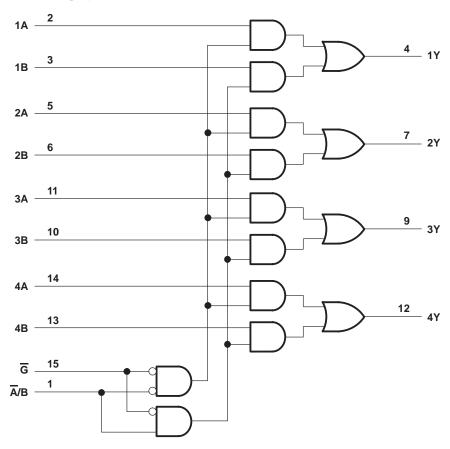


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logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V _{CC}	
Input voltage range, V _I (see Note 1)	
Output voltage range, V _O (see Notes 1 and 2)	$-0.5 \text{ V to V}_{CC} + 0.5 \text{ V}$
Input clamp current, I _{IK} (V _I < 0)	–50 mA
Output clamp current, I _{OK} (V _O < 0)	–50 mA
Continuous output current, IO	±50 mA
Continuous current through V _{CC} or GND	±100 mA
Package thermal impedance, θ _{JA} (see Note 3): D package	73°C/W
PW package	108°C/W
Storage temperature range, T _{stg}	–65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output current ratings are observed.
 - 2. The value of V_{CC} is provided in the recommended operating conditions table.
 - 3. The package thermal impedance is calculated in accordance with JESD 51-7.



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recommended operating conditions (see Note 4)

			MIN	MAX	UNIT
.,	O mark worth and	Operating	2	3.6	
VCC	Supply voltage	Data retention only	1.5		V
VIH	High-level input voltage	$V_{CC} = 2.7 \text{ V to } 3.6 \text{ V}$	2		V
V_{IL}	Low-level input voltage	$V_{CC} = 2.7 \text{ V to } 3.6 \text{ V}$		8.0	V
٧ _I	Input voltage		0	5.5	V
VO	Output voltage		0	VCC	V
	LPak book admit compart	$V_{CC} = 2.7 \text{ V}$		-12	4
ЮН	High-level output current	V _{CC} = 3 V		-24	mA
	Laveland autout anneat	$V_{CC} = 2.7 \text{ V}$		12	A
lOL	Low-level output current	V _{CC} = 3 V		24	mA
Δt/Δν	Input transition rise or fall rate			10	ns/V
T _A	Operating free-air temperature		-40	125	°C

NOTE 4: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARA	METER	TEST CONDITIONS	Vcc	MIN	MAX	UNIT
		$I_{OH} = -100 \mu\text{A}$	2.7 V to 3.6 V	V _{CC} -0.2		
.,		104	2.7 V	2.2		.,
VOH		$I_{OH} = -12 \text{ mA}$	3 V	2.4		V
		$I_{OH} = -24 \text{ mA}$	3 V	2.2		
		$I_{OL} = 100 \mu\text{A}$	2.7 V to 3.6 V		0.2	
VOL		I _{OL} = 12 mA	2.7 V		0.4	V
		I _{OL} = 24 mA	3 V		0.55	
lį	All inputs	V _I = 5.5 V or GND	3.6 V		±5	μΑ
Icc		$V_I = V_{CC}$ or GND, $I_O = 0$	3.6 V		10	μΑ
ΔlCC		One input at V _{CC} – 0.6 V, Other inputs at V _{CC} or GND	2.7 V to 3.6 V		500	μΑ

switching characteristics over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1)

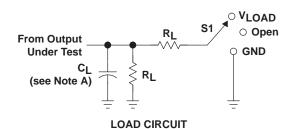
PARAMETER	FROM (INPUT)	TO (OUTPUT)	VCC =	2.7 V	V _{CC} = ± 0.3	UNIT	
	(INFOT)	(001701)	MIN	MAX	MIN	MAX	
	A or B			6.2	0.8	5.4	
t _{pd}	Ā/B	Υ		8.2	0.8	7	ns
·	IG			7.8	0.8	6.5	

operating characteristics, T_A = 25°C

	PARAMETER	TEST	V _{CC} = 2.5 V	V _{CC} = 3.3 V	UNIT
	FARAMETER	CONDITIONS	TYP	TYP	UNII
C _{pd}	Power dissipation capacitance	f = 10 MHz	15	16	pF

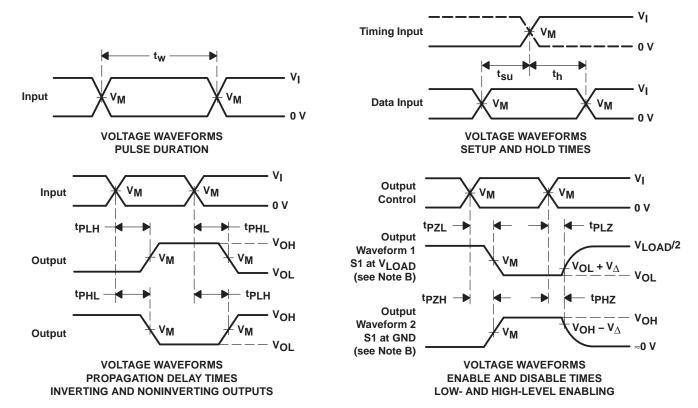


PARAMETER MEASUREMENT INFORMATION



TEST	S1
tPLH/tPHL tPLZ/tPZL	Open V _{LOAD}
tPHZ/tPZH	GND

	INPUTS		.,		_	-	.,
VCC	٧ı	t _r /t _f	V _M	VLOAD	CL	R_L	$v_{\scriptscriptstyle{\Delta}}$
2.7 V 3.3 V ± 0.3 V	2.7 V 2.7 V	≤2.5 ns ≤2.5 ns	1.5 V 1.5 V	6 V 6 V	50 pF 50 pF	500 Ω 500 Ω	0.3 V 0.3 V



- NOTES: A. C_I includes probe and jig capacitance.
 - B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
 - C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_O = 50 \Omega$.
 - D. The outputs are measured one at a time, with one transition per measurement.
 - E. tpLz and tpHz are the same as tdis.
 - F. tpzI and tpzH are the same as ten.
 - G. tpLH and tpHL are the same as tpd.
 - H. All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms





PACKAGE OPTION ADDENDUM

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PACKAGING INFORMATION

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Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
SN74LVC157AQDREP	ACTIVE	SOIC	D	16	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	C157AEP	Samples
SN74LVC157AQPWREP	ACTIVE	TSSOP	PW	16	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	C157AEP	Samples
V62/04659-01XE	ACTIVE	SOIC	D	16	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	C157AEP	Samples
V62/04659-01YE	ACTIVE	TSSOP	PW	16	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	C157AEP	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead finish/Ball material Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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OTHER QUALIFIED VERSIONS OF SN74LVC157A-EP:

Catalog: SN74LVC157A

Automotive: SN74LVC157A-Q1

Military: SN54LVC157A

NOTE: Qualified Version Definitions:

- Catalog TI's standard catalog product
- Automotive Q100 devices qualified for high-reliability automotive applications targeting zero defects
- Military QML certified for Military and Defense Applications

PACKAGE MATERIALS INFORMATION

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TAPE AND REEL INFORMATION





	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LVC157AQDREP	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
SN74LVC157AQPWREP	TSSOP	PW	16	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1

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*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LVC157AQDREP	SOIC	D	16	2500	340.5	336.1	32.0
SN74LVC157AQPWREP	TSSOP	PW	16	2000	853.0	449.0	35.0

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